



### Typical Applications

The HMC995LP5GE is ideal for:

- Point-to-Point Radios
- Point-to-Multi-Point Radios
- VSAT & SATCOM
- Military & Space

#### **Features**

Intergrated Power Detector

Saturated Output Power: 35.5 dBm @ 24% PAE

High Output IP3: 41 dBm

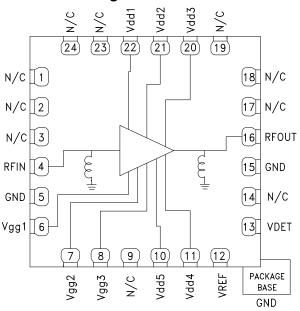
High Gain: 27 dB

DC Supply: +5V to +7V @ 1200 mA No External Matching Required

# General Description

The HMC995LP5GE is a 4 stage GaAs pHEMT MMIC 2 Watt Power Amplifier with an integrated temperature compensated on-chip power detector which operates between 12 and 16 GHz. The HMC995LP5GE provides 27 dB of gain, 35.5 dBm of saturated output power, and 24% PAE from a +7V supply. The HMC995LP5GE exhibits excellent linearity and is optimized for high capacity digital microwave radio. It is also ideal for 13.75 to 14.5 GHz Ku Band VSAT transmitters as well as SATCOM applications. The HMC995LP5GE amplifier I/Os are internally matched to 50 Ohms and is packaged in a leadless QFN 5x5 mm surface mount package and requires no external matching components.

### **Functional Diagram**



## **Electrical Specifications**

 $T_{A} = +25^{\circ} \text{ C}$ , Vdd = Vdd1 = Vdd2 = Vdd3 = Vdd4 = Vdd5 = +7V, Idd = 1200 mA [1]

| Parameter                                | Min.    | Тур. | Max. | Units  |
|--|---------|------|------|--------|
| Frequency Range                          | 12 - 16 |      | GHz  |        |
| Gain [3]                                 | 24      | 27   |      | dB     |
| Gain Variation Over Temperature          |         | 0.03 |      | dB/ °C |
| Input Return Loss                        |         | 9    |      | dB     |
| Output Return Loss                       |         | 15   |      | dB     |
| Output Power for 1 dB Compression (P1dB) | 32      | 34.5 |      | dBm    |
| Saturated Output Power (Psat)            |         | 35.5 |      | dBm    |
| Output Third Order Intercept (IP3)[2]    |         | 41   |      | dBm    |
| Total Supply Current (Idd)               |         | 1200 |      | mA     |

<sup>[1]</sup> Adjust (Vgg1=Vgg2=Vgg3) between -2 to 0V to achieve Idd = 1200mA typical.

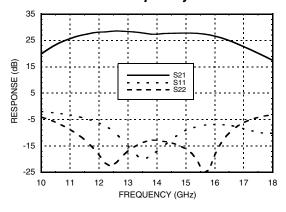
<sup>[2]</sup> Measurement taken at +7V @ 1200mA, Pout / Tone = +22 dBm

<sup>[3]</sup> Board loss subtracted out

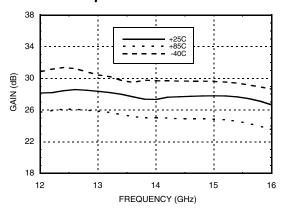




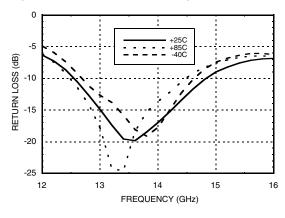
# Broadband Gain & Return Loss vs. Frequency



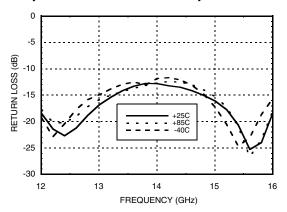
### Gain vs. Temperature [1]



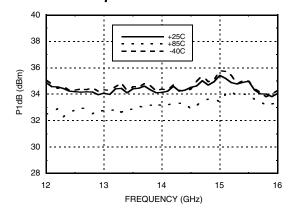
### Input Return Loss vs. Temperature



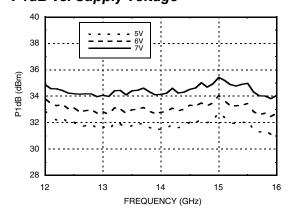
### **Output Return Loss vs. Temperature**



### P1dB vs. Temperature



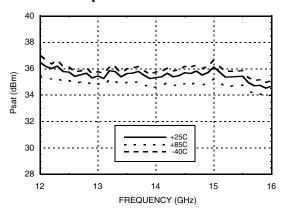
## P1dB vs. Supply Voltage



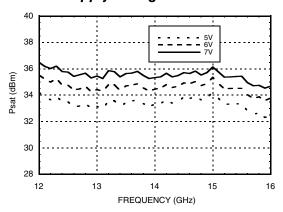




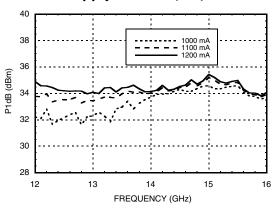
#### Psat vs. Temperature



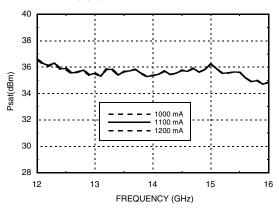
### Psat vs. Supply Voltage



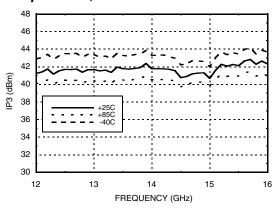
### P1dB vs. Supply Current (Idd)



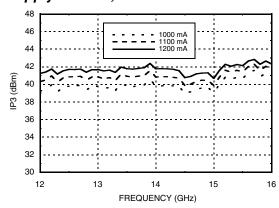
Psat vs. Supply Current (Idd)



# Output IP3 vs. Temperature, Pout/Tone = +22 dBm



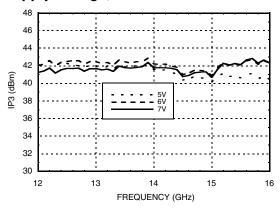
Output IP3 vs.
Supply Current, Pout/Tone = +22 dBm



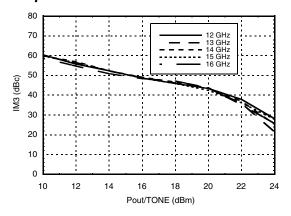




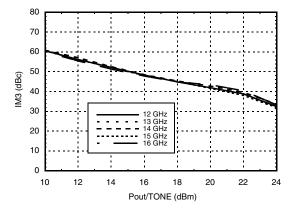
Output IP3 vs. Supply Voltage, Pout/Tone = +22 dBm



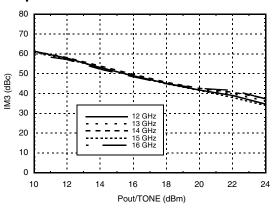
Output IM3 @ Vdd = +5V



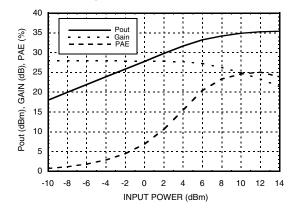
**Output IM3 @ Vdd = +6V** 



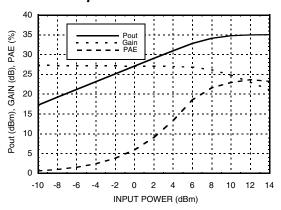
Output IM3 @ Vdd = +7V



### Power Compression @ 13 GHz



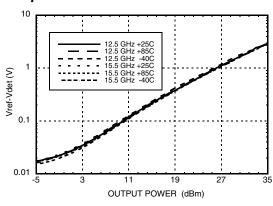
### Power Compression @ 15 GHz



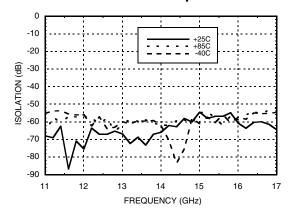




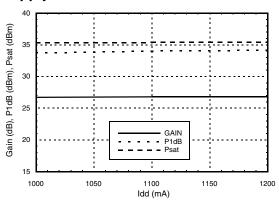
# Detector Voltage vs. Frequency & Temperature



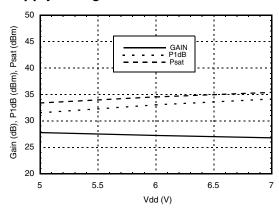
### Reverse isolation vs. Temperature



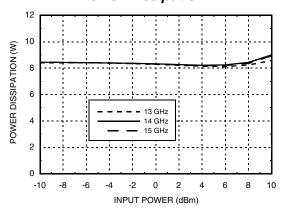
## Gain & Power vs. Supply Current @ 14 GHz



### Gain & Power vs. Supply Voltage @ 14 GHz



### **Power Dissipation**







### **Absolute Maximum Ratings**

| Drain Bias Voltage (Vdd1-5)                                   | +8V            |
|---|----------------|
| RF Input Power (RFIN)   | +24 dBm        |
| Channel Temperature   | 150 °C         |
| Continuous Pdiss (T= 85 °C)<br>(derate 137 mW/°C above 85 °C) | 8.9 W          |
| Thermal Resistance (channel to gnd paddle)                    | 7.3 °C/W       |
| Storage Temperature   | -65 to +150 °C |
| Operating Temperature   | -40 to +85 °C  |
| ESD Sensitivity (HBM)   | Class 1A       |

### Typical Supply Current vs. Vdd

| Vdd (V) | Idd (mA) |
|---------|----------|
| 5       | 1200     |
| 6       | 1200     |
| 7       | 1200     |

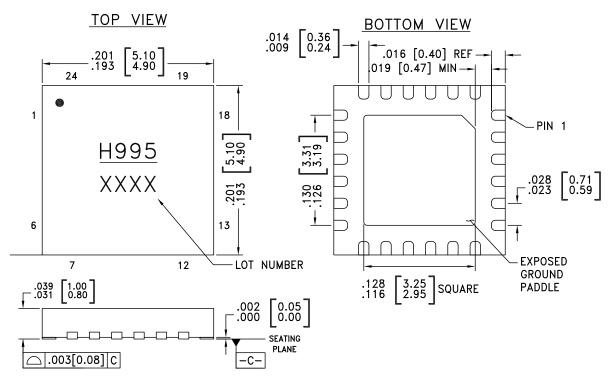
Note: Amplifier will operate over full voltage ranges shown above Vgg adjusted to achieve Idd = 1200 mA







## **Outline Drawing**



#### NOTES:

- 1. PACKAGE BODY MATERIAL: ALUMINA
- 2. LEAD AND GROUND PADDLE PLATING: 30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM -C-
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

### Package Information

| Part Number | Package Body Material                              | Lead Finish   | MSL Rating          | Package Marking [1] |
|-------------|--|---------------|---------------------|---------------------|
| HMC995LP5GE | RoHS-compliant Low Stress Injection Molded Plastic | 100% matte Sn | MSL3 <sup>[2]</sup> | <u>H995</u><br>XXXX |

<sup>[1] 4-</sup>Digit lot number XXXX

[2] Max peak reflow temperature of 260  $^{\circ}\text{C}$ 





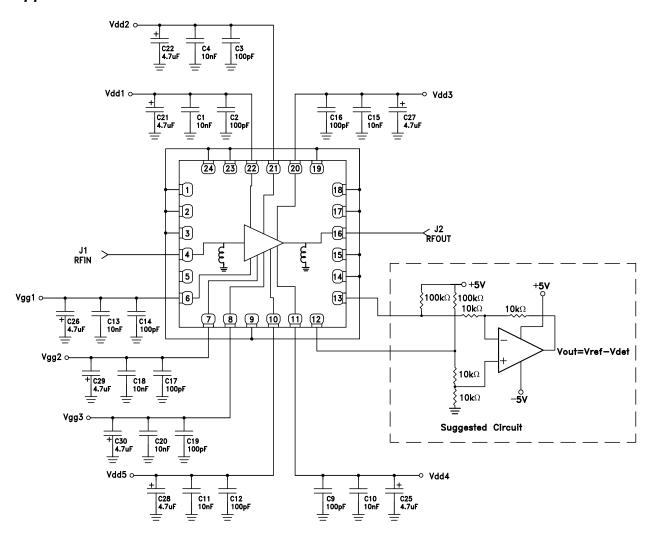
## **Pin Descriptions**

| Pin Number                  | Function                        | Description   | Interface Schematic |
|-----------------------------|---------------------------------|---|---------------------|
| 1-3, 9, 14<br>17-19, 23, 24 | N/C                             | These pins are not connected internally, however all data shown herein was measured with these pins connected to RF/DC ground externally.                 |                     |
| 4                           | RFIN                            | This pad is DC coupled and matched to 50 Ohms.  | RFIN O              |
| 5, 15                       | GND                             | These pins and package bottom must be connected to RF/DC ground.  | GND<br>=            |
| 6-8                         | Vgg1, Vgg2<br>Vgg3              | Gate control for amplifier. External bypass capacitors of 100pF, 10nF and 4.7uF are required. Please follow "MMIC Amplifier Biasing Proceedure" App Note. | Vgg1-3              |
| 10, 11<br>20-22             | Vdd1, Vdd2,<br>Vdd3, Vdd4, Vdd5 | Drain bias voltage for the amplifier. External bypass capacitors of 100pF, 10nF and 4.7μF capacitors are required.  | Vdd1-5              |
| 12                          | Vref                            | DC voltage of diode biased through external resistor, used for temperature compensation of Vdet. See Application Circuit.                                 |                     |
| 13                          | Vdet                            | DC voltage representing RF output power rectified by diode which is biased through an external resistor. See Appilation Circuit.                          |                     |
| 16                          | RFOUT                           | This pin is DC coupled and matched to 50 Ohms.  | RFOUT               |





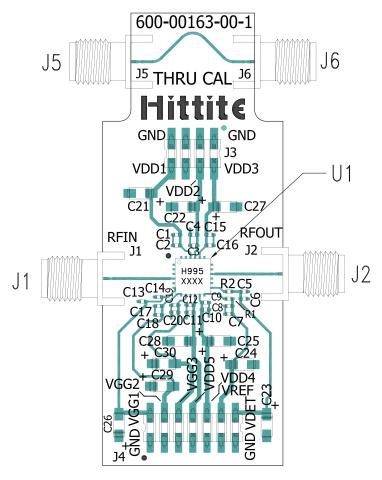
## **Application Circuit**







#### **Evaluation PCB**



### List of Materials for Evaluation PCB EVAL01-HMC995LP5GE [1]

| Item                                       | Description                 |
|--|-----------------------------|
| J1, J2, J5, J6                             | K Connector SRI             |
| J3, J4                                     | DC Pin                      |
| C2, C3, C9, C12,<br>C14, C16, C17,<br>C19  | 100 pF Capacitor, 0402 Pkg. |
| C1, C4, C10, C11,<br>C13, C15, C18,<br>C20 | 10 nF Capacitor, 0402 Pkg.  |
| C21, C22, C25<br>- C30                     | 4.7uF Capacitor, Case A.    |
| U1   | HMC995LP5GE Power Amplifier |
| PCB  | 600-00163-00 Evaluation PCB |

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

<sup>[2]</sup> Circuit Board Material: Rogers 4350 or Arlon FR4